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Dr. Dahiya holds prestigious EPSRC Fellowship. In past, he received Marie Curie Fellowship and Japanese Monbusho Fellowship. He was awarded with the University Gold Medal and received 2 best paper awards and 2 second best paper awards (as co-author) in IEEE international conferences. He received the 2016 IEEE Sensor Council Technical Achievement Award, the 2016 Microelectronic Engineering Young Investigator Award, and International Association of Advanced Materials (IAAMM) Medal for the year 2016. In 2016, he was included in list of Scottish 40UNDER40.